1						
PCN Number:	20171025001	_	Date:	Nove	mber 1	.7, 2017
	MSP432P401R	, MSP432P401M		1		
Customer Contact:	PCN Manager			De	pt:	Quality Services
Change Type:						
Assembly Site		Design				Bump Site
Assembly Process		Data Sheet			Wafer	Bump Material
Assembly Materials		Part number cha	inge	Щ		Bump Process
Mechanical Specific		Test Site				Fab Site
Packing/Shipping/L	_abeling	Test Process		Щ		Fab Materials
					Wafer	Fab Process
		tification De	tails			
<b>Description of Chang</b> Texas Instruments Inco						
The product datasheet(s) is being updated as summarized below.  The following change history provides further details.  MSP432P401R MSP432P401M						
INSTRUMENTS			SLAS			P401R, MSP432P401M 15-REVISED SEPTEMBER 2017
Changes from March 8, 201	7 to September 26,	2017				Page
<ul> <li>Updated Section 1.3, Description.</li> <li>Changed the name of the ADC module from ADC14 to Precision ADC throughout document</li> <li>Added VSW to Table 4-4, Connection for Unused Pins</li> <li>Removed MAX values from Section 5.21 and Section 5.22</li> <li>Added Section 5.25.2, Peripheral Register Access Timing</li> <li>Changed the MAX value of the df<sub>DCO</sub>/dT parameter in external resistor mode to 60 ppm/°C in Table 5-12, DCO</li> <li>Changed the MAX value of the ff<sub>VLO</sub> parameter to 18 kHz in Table 5-14, Internal Very-Low-Power Low-Frequency Oscillator (VLO)</li> <li>Changed the MAX value of the "REFO absolute tolerance calibrated" parameter at T<sub>A</sub> = -40°C to 85°C to ±4% in Table 5-15, Internal-Reference Low-Frequency Oscillator (REFO) in 32.768-kHz Mode</li> <li>Changed the TYP and MAX values of the TC<sub>REF+</sub> parameter in Table 5-34, REF_A, Built-In Reference</li> <li>Removed interrupt-related registers from Port 7 to Port 10 in Table 6-21, Port Registers (Base Address: 0x4000_4C00)</li> <li>Corrected the bank 0 address range (changed 0x2000_007FF to 0x2000_07FF) in the last paragraph in Section 6.4.2.2, SRAM Bank Retention Configuration and Backup Memory</li> <li>Clariffed DMA access to flash banks in Section 6.5.3, DMA Access Privileges</li> <li>Corrected the memonics for the timer functions in Table 6-44 and Table 6-45</li> <li>Corrected the ADC channel mapping for the Battery Monitor and Temperature Sensor in Table 6-53, Precision ADC Channel Mapping on 64-Pin RGC Devices</li> <li>133</li> </ul>						
The datasheet number	will be changing					
Device Family		Change From:			Chang	e To:
MSP432P401R, MSP4	32P401M	SLAS826F			SLAS8	26G
These changes may be reviewed at the datasheet links provided.						
http://www.ti.com/product/MSP432P401R						
Reason for Change:						
Improve the device's description and more accurately reflect device characteristics.						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):						
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.						
Changes to product in	dentification re	esulting from tl	nis PCN:			
None						

Product Affected:									
	MSP432P401MIPZ	MSP432P401MIPZR	MSP432P401MIRGCR	MSP432P401MIRGCT					
	MSP432P401MIZXHR	MSP432P401MIZXHT	MSP432P401RIPZ	MSP432P401RIPZR					
	MSP432P401RIRGCR	MSP432P401RIRGCT	MSP432P401RIZXHR	MSP432P401RIZXHT					

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